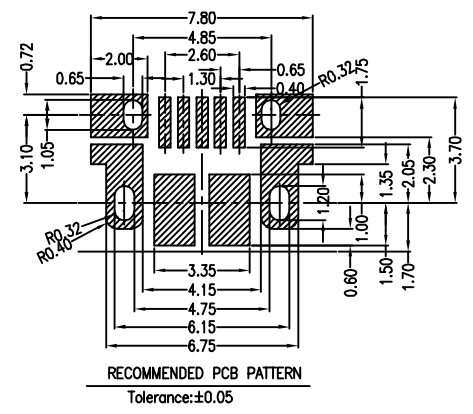
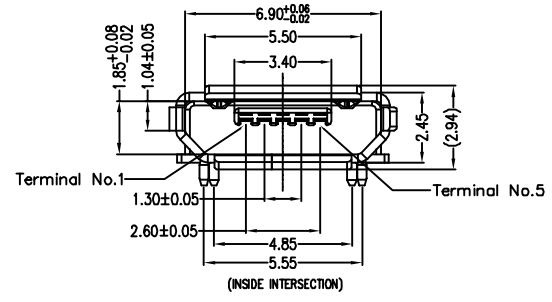
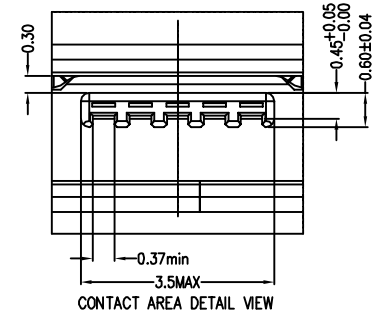
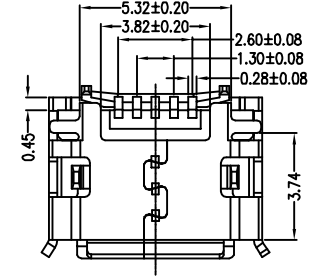
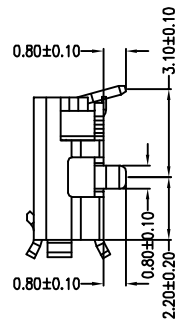
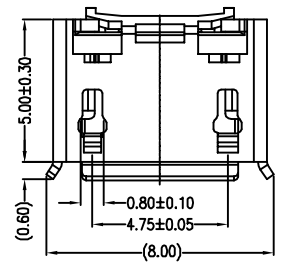
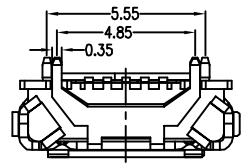
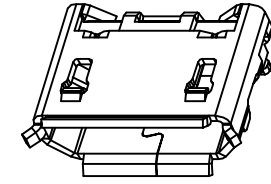


REV.	ECN.NO.	APPD.
AO	/	/



Note:
 1.Material:
 1.1 Housing: LCP High temperature thermoplastic with g.f,UL94v-0
 1.2 Contact: copper alloy,t=0.15mm
 1.3 Shell: SUS304,t=0.30mm
 2.Specification:
 2.1 Current rating: 1 A Max.
 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 2.3 Contact resistance: 50 mW Max.
 2.4 Insulation resistance: 100 MW Min.
 2.5 Total mating force: 3.57 Kgf Max.
 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.
 2.7 Temperature range: -30°C~80°C

U448-071X-XXX0X8

- 1: 铁壳镀镍
- 5: 铜壳镀镍
- 4: 铁壳镀金
- 6: 铜壳镀锡
- 1: 半金1u"
- 3: 半金3u"
- G: G/F
- 1: 吸塑盒
- 3: 冷封载带
- 8: 热封载带
- 1: 黑色
- 3: 米黄色
- 1: PA66
- 2: PBT
- 6: LCP

TOLERANCE UNLESS OTHERWISE SPECIFIED		FLW 深圳市华联威电子科技有限公司				
.XXX ±0.10		HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.				
.XX ±0.20		.X' ±3'				
.X ±0.30		.XX' ±2'				
APPROVED		PART NAME:	MICRO 5P/F B型牛角5.55			
CHECKED		PART No:	U448-0716-G61038	C		
DRAWN	wei hong	PROJECTION:	UNIT:	SCALE:	SHEET:	
DATE	2021. 7. 30		mm	1:1	10F1	
					REV. AO	